

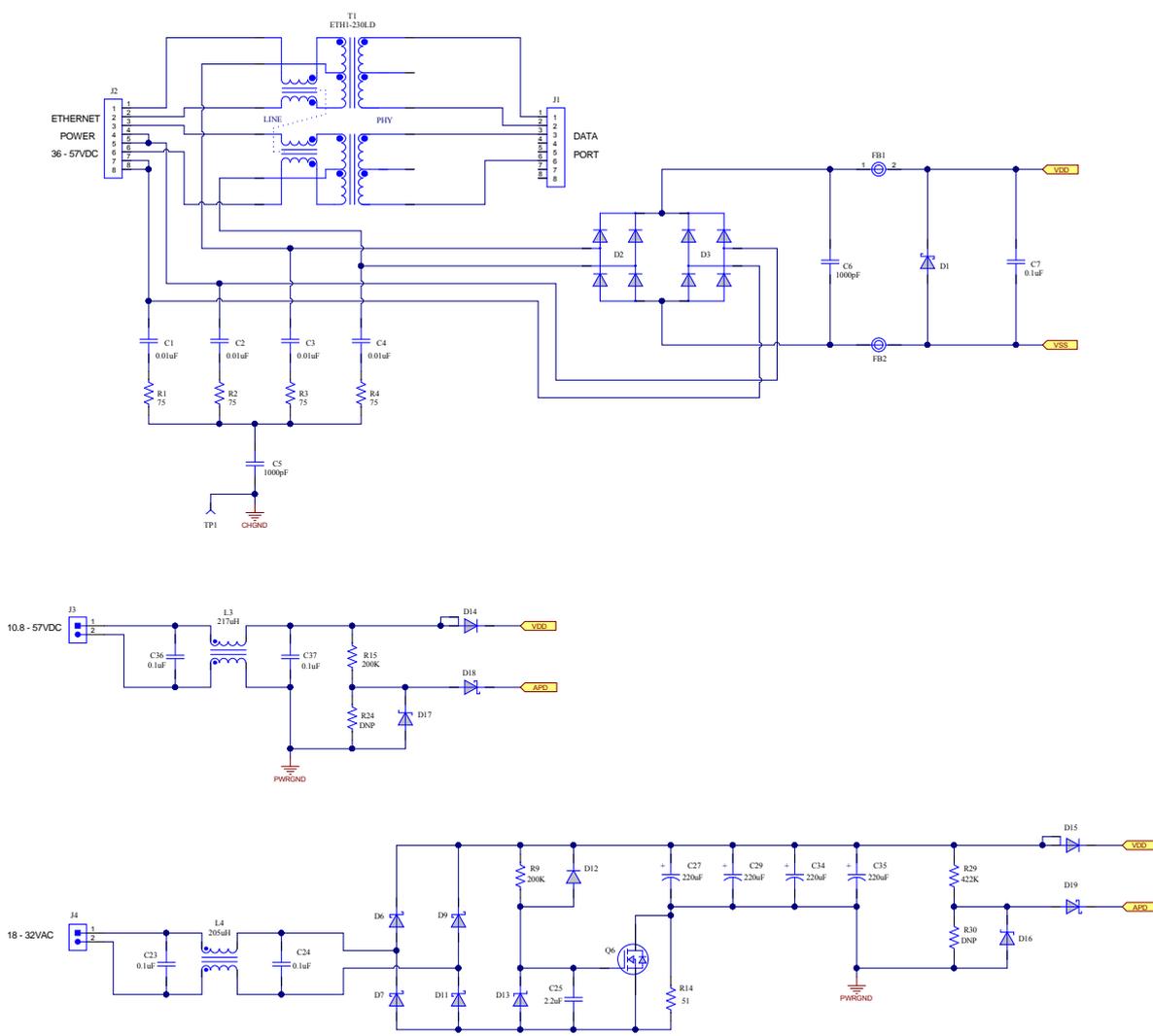
Revision History	
Revision	Notes

Place Block Diagram here (if appropriate) or delete this text box.
 If using a block diagram from another tool, save the picture as a .bmp
 file.
 Then, use menu Place|Drawing Tools|Graphic to insert the .bmp file on
 the schematic.

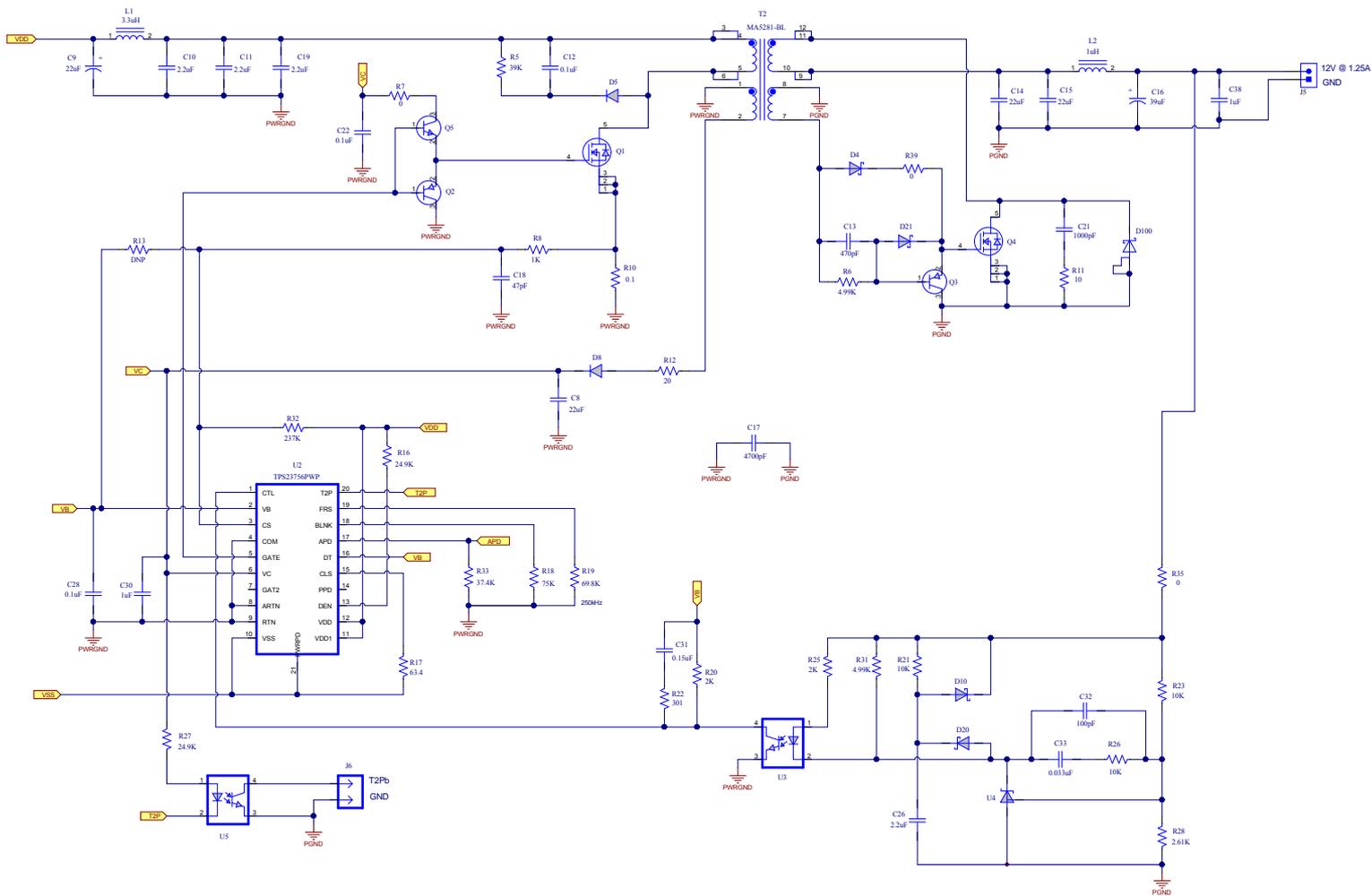
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Designed for: Public Release		Mod. Date: 1/9/2014	
Number: PMP6659		Rev: B	
Project Title: PMP6659B		Sheet Title: PMP6659	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	
Drawn By: Ajinder Singh		File: PMP6659B_CVR.SchDoc	
Engineer: Ajinder Singh		Contact: http://www.ti.com/support	
		Sheet: 1 of 4	
		Size: B	
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1 2 3 4 5 6

A

A



FID1

PCB Number: PMP6659
PCB Rev: B



FID2



FID3

B

B

C

C

ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

D

D

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Drawn By: Ainder Singh		File: PMP6659B_HDWR_SchDoc	
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